



74AHCT1G00Q

#### SINGLE 2-INPUT POSITIVE NAND GATE

### Description

The 74AHCT1G00Q is an automotive compliant single, two-input positive NAND gate with a standard push-pull output. The device is designed for operation with a power supply range of 4.5V to 5.5V. The gate performs the positive Boolean function:

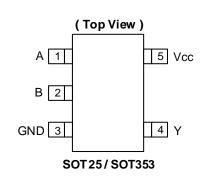
$$Y = \overline{A \cdot B}$$
 or  $Y = \overline{A} + \overline{B}$ 

#### Features

- Grade 1 Ambient Temperature Operation: -40°C to +125°C
- Supply Voltage Range from 4.5V to 5.5V
- ±8mA Output Drive at 5.0V
- CMOS Low-Power Consumption
- High Noise Immunity
- Inputs Not Limited by V<sub>CC</sub>
- Balanced Propagation Delays
- Balanced Drive Capability
- ESD Protection Tested per AEC-Q100
- Exceeds 2000V Human Body Model (AEC-Q100-002)
- Exceeds 1000V Charged Device Model (AEC-Q100-011)
- Latch-Up Exceeds 100mA (AEC-Q100-004)
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The 74AHCT1G00Q is suitable for automotive applications requiring specific change control; this part is AEC-Q100 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

https://www.diodes.com/quality/product-definitions/

## Pin Assignments



### Applications

- General purpose logics
  - Wide array of products, such as:
    - Automotive applications within grade 1 temperature range
    - Industrial computing/controls/automations
    - High reliability networking/communications
    - Industrial/Agricultural equipment

- Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  - 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  - 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.



### **Pin Descriptions**

Pin Name	Description
А	Data Input
В	Data Input
GND	Ground
Y	Data Output
Vcc	Supply Voltage

### **Function Table**

Inp	Output	
Α	В	Y
Н	Н	L
L	Х	Н
Х	L	Н

### Absolute Maximum Ratings (Notes 4 & 5)

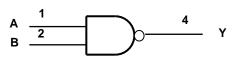
Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
Vcc	Supply Voltage Range	-0.5 to 6.5	V
VI	Input Voltage Range	-0.5 to 6.5	V
Vo	Voltage Applied to Output in High or Low State	-0.5 to V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input Clamp Current VI < 0	-20	
Іок	Output Clamp Current (Vo < 0 or Vo > Vcc)	±20	mA
lo	Continuous Output Current (Vo = 0 to Vcc)	±25	mA
Icc	Continuous Current Through Vcc	75	mA
Ignd	Continuous Current Through GND	-75	mA
T <sub>J</sub> Operating Junction Temperature		-40 to +150	°C
T <sub>STG</sub> Storage Temperature		-65 to +150	°C
PD Total Power Dissipation (Note 6)		250	mW

4. Stresses beyond the absolute maximum can result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

5. Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.

6. This will need to be derated at higher operating temperatures to prevent exceeding maximum T<sub>J</sub>. Refer to package thermal characteristics section.

## Logic Diagram



Notes:



## Recommended Operating Conditions (Note 7)

Symbol	Pa	rameter	Min	Max	Unit
Vcc	Operating Voltage	—	4.5	5.5	V
VIH	High-Level Input Voltage	$V_{CC} = 5V \pm 0.5V$	2.0	_	V
VIL	Low-Level Input Voltage	$V_{CC} = 5V \pm 0.5V$	—	0.8	V
Vı	Input Voltage	0	5.5	V	
Vo	Output Voltage		0	Vcc	V
Іон	High-Level Output Current	$V_{CC} = 5V \pm 0.5V$	_	-8	mA
IOL	Low-Level Output Current	$V_{CC} = 5V \pm 0.5V$	_	8	mA
Δt/ΔV	Input Transition Rise or Fall Rate Vcc = 5V ± 0.5V		_	20	ns/V
TA	Ambient Temperature	_	-40	+125	°C

Note: 7. Unused inputs should be held at  $V_{CC}$  or Ground.

### Electrical Characteristics (All typical values are at V<sub>CC</sub> = 5V, T<sub>A</sub> = +25°C.)

					+25°C		-40°C to	o +85°C	-40°C to	• +125°C	
Symbol	Parameter	Test Conditions	Vcc	Min	Тур	Max	Min	Max	Min	Max	Unit
N	High Level Output	VI = VIH or VIL I <sub>OH</sub> = -50µA	4.5V	4.4	4.5	_	4.4	_	4.4	_	V
V <sub>OH</sub>	Voltage	VI = VIH or VIL IOH = -8mA	4.5V	3.94	_	_	3.8	_	3.70	_	V
	Low Level Output	VI = VIH or VIL I <sub>OL</sub> = 50µA	4.5V		0	0.1	-	0.1	_	0.1	V
VOL	V <sub>OL</sub> Voltage	$V_{I} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 8mA$	4.5V		_	0.36		0.44	_	0.55	V
Ц	Input Current	$V_1 = 5.5 V$ or GND	0V to 5.5V		_	±0.1		±1	—	±2	μA
∆lcc	Additional Supply Current	Per input pin, $V_I = 3.4V$ , Other inputs at V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5V	I	_	1.35	_	1.5	_	1.5	mA
Icc	Supply Current	$V_I = 5.5V \text{ or GND}$ $I_O = 0$	5.5V			1		10	_	40	μA
CI	Input Capacitance	$V_I = V_{CC}$ or GND	5.5V	_	1.5	10	_	10	_	10	pF



## **Package Characteristics**

Symbol	Parameter	Package	Test Conditions	Min	Тур	Max	Unit
0	Thermal Resistance	SOT25	Niete O		184	—	2044
θја	Junction-to-Ambient	SOT353	Note 8		385	—	°C/W
0	Thermal Resistance	SOT25	Niete O		62	—	0000
θις	Junction-to-Case	SOT353	Note 8		164	—	°C/W

Note: 8. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

## **Switching Characteristics**

Vcc = 5V  $\pm$  0.5V (See Figure 1, Typical Values at Vcc = 5V.)

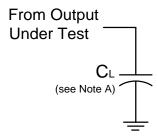
	From	То	Test	+25°C		-40°C to +85°C		-40°C to +125°C			
Parameter	(Input)	(Output) Condit	Conditions	Min	Тур	Max	Min	Max	Min	Max	Unit
			C∟ = 15pF	1.0	3.6	6.2	1.0	7.1	1.0	8.0	ns
tpd	A or B	Ŷ	$C_L = 50 pF$	1.0	5.0	7.9	1.0	9.0	1.0	10.0	ns

## **Operating Characteristics**

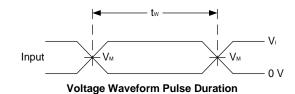
T <sub>A</sub> = +25°C				
	Parameter	Test Conditions	Vcc = 5V Typ	Unit
Cpd	Power Dissipation Capacitance	f = 1MHz No Load	10	pF

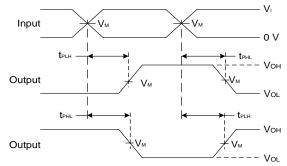


### **Measurement Information**



Vcc		Inputs		Output	CL
•00	Vi	tr/tr	Vм	Vм	σL
5V±0.5V	GND to Vcc	≤3ns	1.5V	Vcc/2	15pF
5V±0.5V	GND to Vcc	≤3ns	1.5V	Vcc/2	50pF





Voltage Waveform Propagation Delay Times Inverting and Non-Inverting Outputs

Figure 1. Load Circuit and Voltage Waveforms

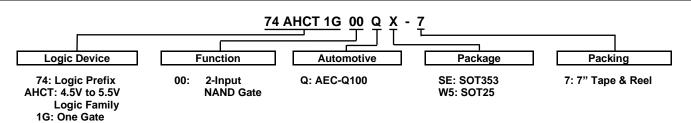
Notes:

- A. Includes test lead and test apparatus capacitance.
  B. All pulses are supplied at pulse repetition rate ≤ 1MHz.
  C. Inputs are measured separately one transition per measurement.

D.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{PD}$ .



# Ordering Information (Note 9)



Part Number	Package	Package	Package Size	Pac	cking
Fait Nulliber	Code	(Notes 10 & 11)	Fackage Size	Qty.	Carrier
74AHCT1G00QSE-7	SE	SOT353	2.15mm × 2.1mm × 1.1mm 0.65mm Lead Pitch	3000	7" Tape and Reel
74AHCT1G00QW5-7	W5	SOT25	3.0mm × 2.8mm × 1.2mm 0.95mm Lead Pitch	3000	7" Tape and Reel

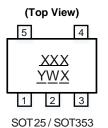
Notes: 9. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

10. Pad layout as shown in Diodes Incorporated's package outline PDFs, which can be found on our website at

http://www.diodes.com/package-outlines.html.

11. The taping orientation is located on our website at https://www.diodes.com/assets/Packaging-Support-Docs/ap02007.pdf.

### **Marking Information**



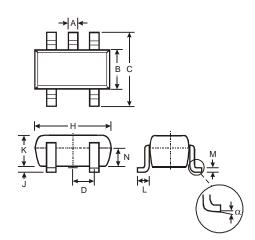
Part Number	Package	Identification Code
74AHCT1G00QW5-7	SOT25	ZRQ
74AHCT1G00QSE-7	SOT353	ZRQ



## **Package Outline Dimensions**

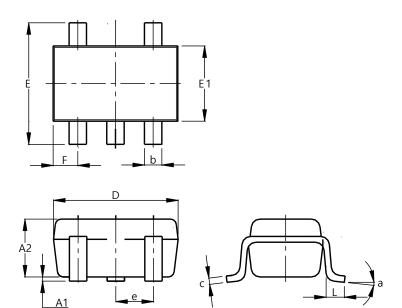
Please see http://www.diodes.com/package-outlines.html for the latest version.

(1) Package Type: SOT25



	SOT25								
Dim	Dim Min Max Typ								
Α	0.35	0.50	0.38						
В	1.50	1.70	1.60						
С	2.70	3.00	2.80						
D	-	-	0.95						
Н	2.90	3.10	3.00						
J	0.013	0.10	0.05						
κ	1.00	1.30	1.10						
L	0.35	0.55	0.40						
М	0.10	0.20	0.15						
Ν	0.70	0.80	0.75						
α	0°	8°	1						
All D	imensi	ons in	mm						

#### (2) Package Type: SOT353



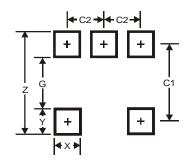
SOT353				
Dim	Min	Max	Тур	
A1	0.00	0.10	0.05	
A2	0.90	1.00	0.95	
b	0.10	0.30	0.25	
с	0.10	0.22	0.11	
D	1.80	2.20	2.15	
Е	2.00	2.20	2.10	
E1	1.15	1.35	1.30	
e	0.650 BSC			
F	0.40	0.45	0.425	
L	0.25	0.40	0.30	
а	0°	8°		
All Dimensions in mm				



## Suggested Pad Layout

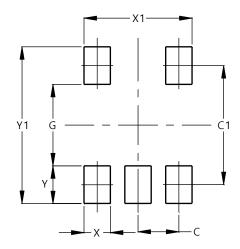
Please see http://www.diodes.com/package-outlines.html for the latest version.

#### (1) Package Type: SOT25



Dimensions	Value	
Z	3.20	
G	1.60	
Х	0.55	
Y	0.80	
C1	2.40	
C2	0.95	

#### (2) Package Type: SOT353



Dimensions	Value (in mm)
С	0.650
C1	1.900
G	1.300
Х	0.420
X1	1.720
Y	0.600
Y1	2.500

#### **Mechanical Data**

#### SOT25

- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208
- Weight: 0.0158 grams (Approximate)

#### SOT353

- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.0064 grams (Approximate)



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